

2.3D Package Substrate ~i-THOP®~

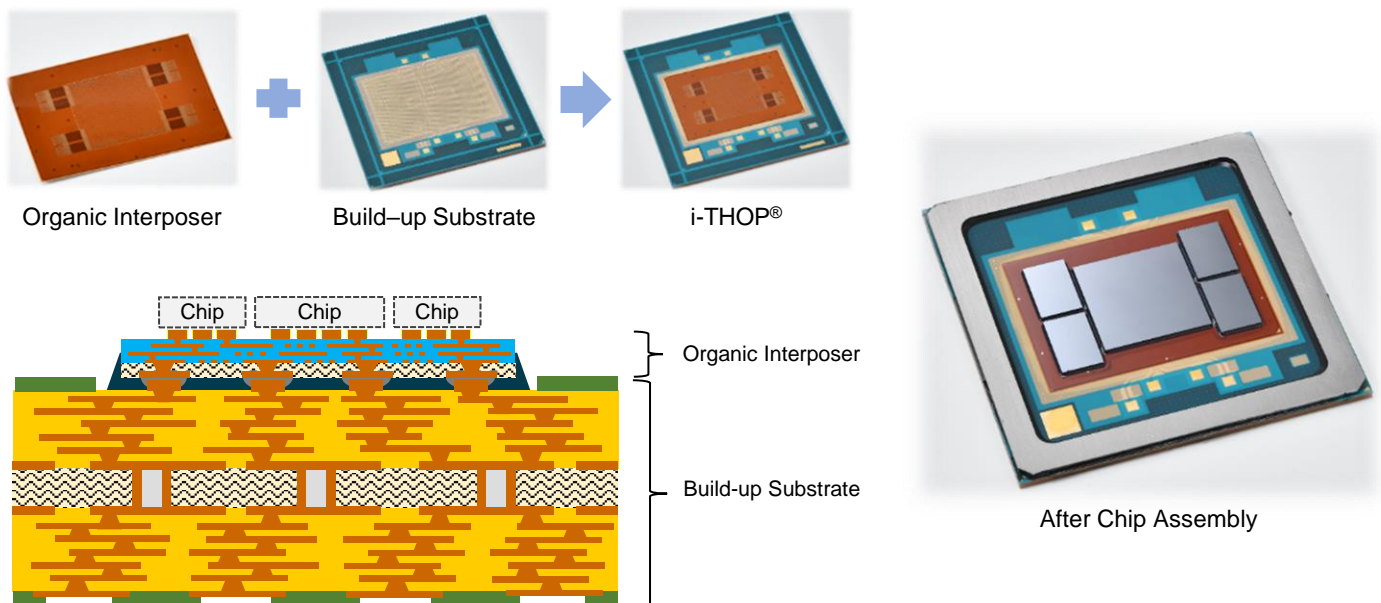
i-THOP (integrated Thin film High density Organic Package) is a registered trademark of SHINKO ELECTRIC INDUSTRIES CO., LTD.

- Under development -

Features

- High density interconnection that includes integrating an organic interposer on a build-up substrate
- Ultra fine line and space (L/S) possible by applying thin film technology to the interposer
- Technology support chip partitioning and HBM (High Bandwidth Memory) connection for system integration

Structure



Technologies

Organic Interposer	
Min. FC (Flip-Chip) Pad Pitch	40 μm
Min. Line/Space	2 / 2 μm
Micro Via Dia.	12 μm
Metal Thickness	2 μm
Insulation Thickness	5 μm
Interposer Joint	
Material	Sn-Bi Solder
Solder Joint Pitch	150 μm

